

ABSTRACT

A wafer carrier is provided comprised of a circular plate having a flat edge region extending around the circumference of the plate. The plate has a circular recessed center region with a recessed bottom surface and includes an upwardly inclined surface around the periphery of the recessed bottom surface. A substrate is placed in the center region where it is supported by a portion of the upwardly inclined surface and is spaced apart from the recessed bottom surface such that the substrate is supported only around its edge. The wafer carrier minimizes surface contact with the substrate thereby minimizing metal contamination and surface damage to the backside of a substrate and prevents deposition on the backside of the substrate.